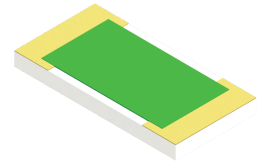


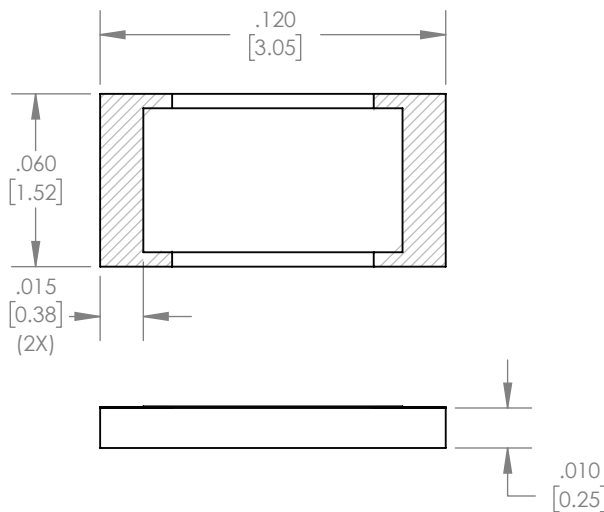
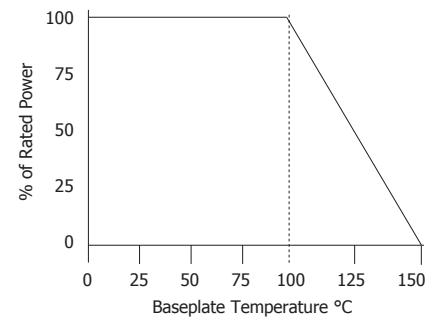
RS1206ZZ-XXXXWN-95 Features:

- Single-Sided (Flip-Chip) Terminal Configuration
- Solder, Epoxy or Wirebondable Terminals
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel (Film Side Down) and Waffle Pack Available (Standard is bulk)


RS1206ZZ-XXXXWN-95 Parameters:

Resistance Range:	0.5Ω - 1MΩ
Rated Power*:	1.5W
Construction:	Thick Film on 0.010" BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RS1206ZZ-XXXXWN-95 Dimensions:

**RS1206ZZ-XXXXWN-95
Power Derating Curve**


Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13]
 unless otherwise stated

Ordering Information:
Example Part Number: RS1206CT-50R0JN-95

RS	1206	ZZ	-	XXXX	W	N	-	95	UU
Prefix for Resistor w/ Single-Sided Terminals				Value Code	Tolerance	<div style="border: 1px dashed black; padding: 5px; text-align: center;"> Normal Inspection Contact factory for additional options </div>	Substrate	Packaging	
Size				50R0 - 50Ω	F - 1%		95 - 0.010" BeO	Blank - Bulk	
1206				1000 - 100Ω	G - 2%			WP - Waffle Pack	
				1001 - 1KΩ	J - 5%			TRD - Tape & Reel	
Terminal Metallization					RoHS	Magnetic	Solder	Epoxy	Wirebond
AS -	Tin Lead over Platinum Palladium Gold				No	No	Yes	No	No
CB -	Tin Lead over Nickel over Silver				No	Yes	Yes	No	No
CC -	100% Matte Tin over Copper over Silver				Yes	No	Yes	No	No
CT -	100% Matte Tin over Nickel over Silver				Yes	Yes	Yes	No	No
JA -	Gold over Platinum Palladium Gold				Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RS1206ZZ-XXXXWN-95 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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